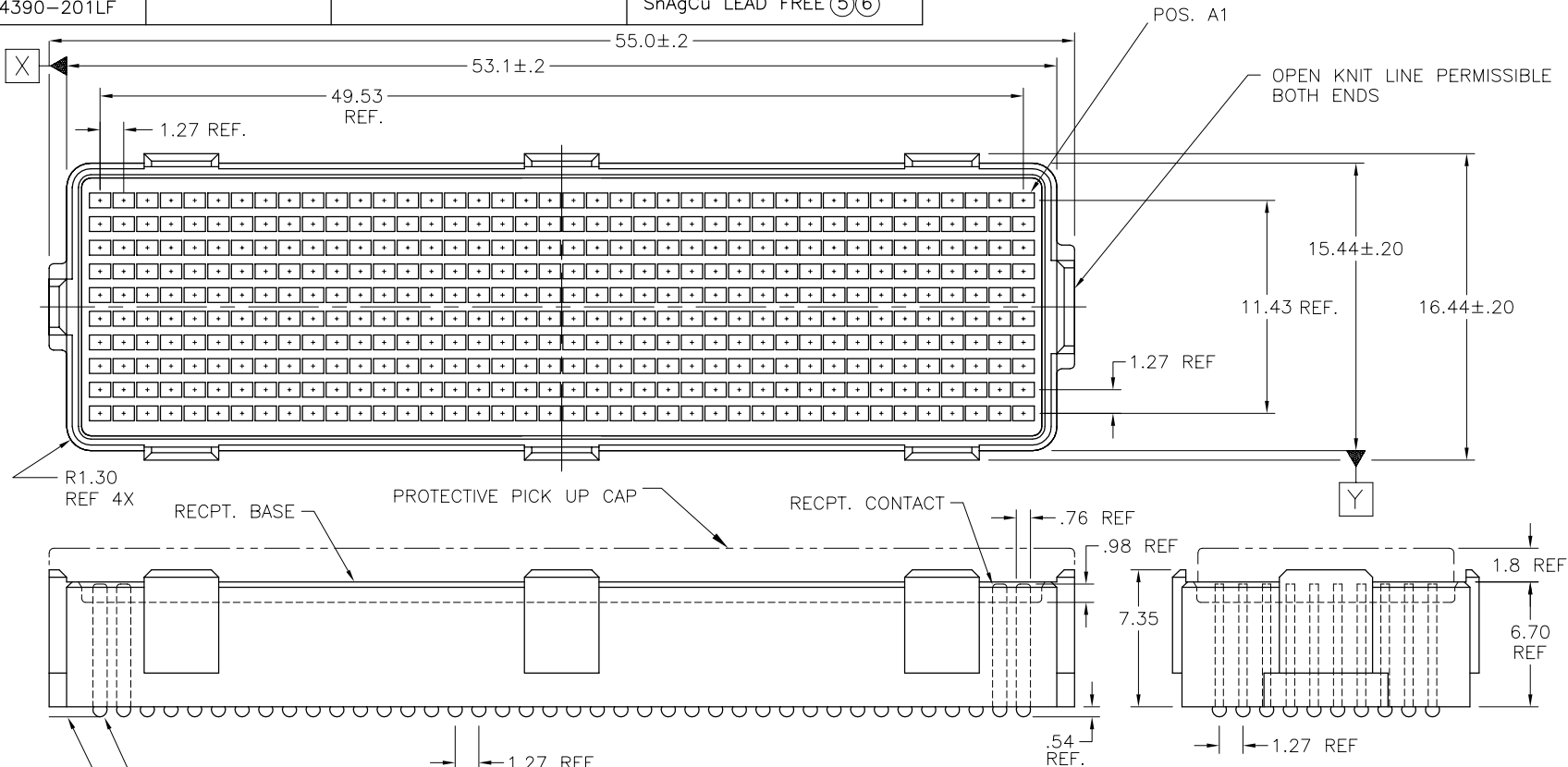
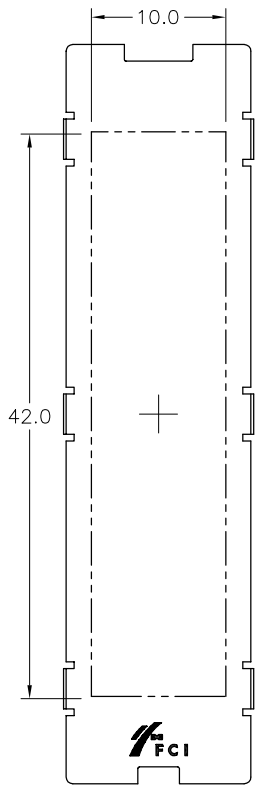


PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
74390-001	YES	15u" (.38um) Au OVER Ni	SnPb
74390-001LF			SnAgCu LEAD FREE (5)(6)
74390-101	YES	30u" (.76um) Au OVER Ni	SnPb
74390-101LF			SnAgCu LEAD FREE (5)(6)
74390-201	YES	SEE NOTE 4.	SnPb
74390-201LF			SnAgCu LEAD FREE (5)(6)

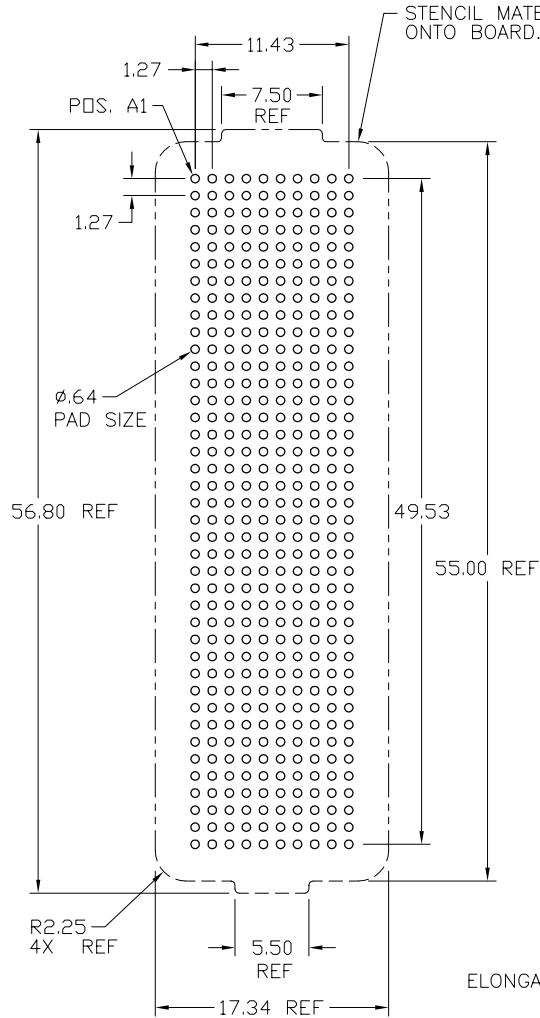


Ø.760 SOLDER BALLS
NOTE 2
⊕ Ø.30 X Y
▱ .203

mat'l. code	SEE NOTE 1	surface	ASME Y14.5 ✓	tolerance	ASME Y14.5	projection	product family	MEG-ARRAY	
ltr	ec'n no	dr	date	tolerances unless otherwise specified		MM	title		
L	V06-0560	LP	2006/06/23	angles	X+3	scale 3:1	8mm RECPT. ASSY		
-	-	-	-	flatness	.XX+13		10 X 40= 400 POS.		
F	V93020	DRW	11/8/99	0° ±2'	XXX+051		dwg no	sheet 1 of 3	
G	V00196	HLJ	7/2/00	dr	D WAUGHEN		1.5.98	size	A4
H	V20006	DRW	1/3/02	engr	T LEMKE		1.5.98	74390	CUSTOMER Drawing
J	V03-0679	DAI	6/19/03	chr	T LEMKE		1.5.98		
K	V04-0940	VS	10/18/04	appd	T LEMKE		1.5.98		
sheet index	revision sheet	L	L	L					

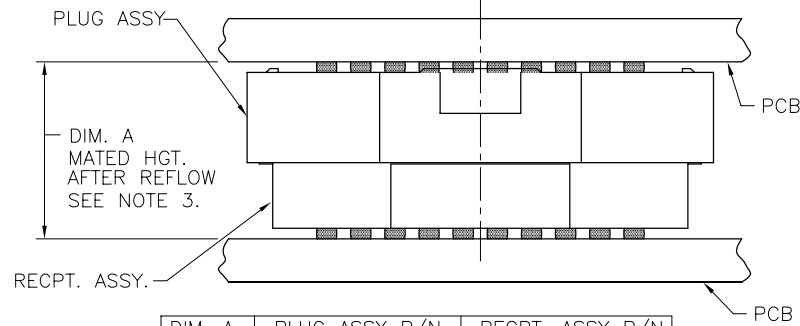


FLAT AREA FOR PICK-UP CAP



BOARD PATTERN SCALE 2/1

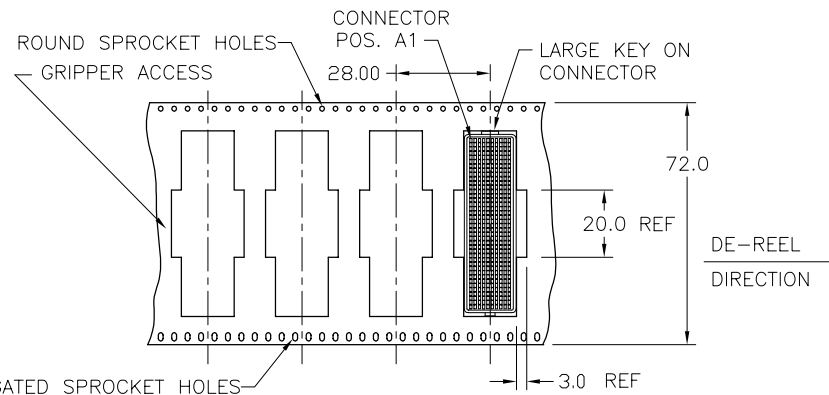
STENCIL MATED CONNECTOR OUTLINE ONTO BOARD.



DIM. A	PLUG ASSY P/N	RECPT. ASSY P/N
8.0	84740	74390
14.0	84520	74390

MATED HEIGHT AFTER REFLOW IS BASED ON Ø .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE



TAPE & REEL PACKAGING SCALE NONE PER EIA 481-3

mat'l. code	SEE NOTE 1	surface	ASME Y14.5 ✓	tolerance	ASME Y14.5	projection		product family	MEG-ARRAY
ltr	ecn no	dr	date	tolerances unless otherwise specified			MM	title	8mm RECPT. ASSY. 10x40= 400 POS.
L				angles	X*3			dwg no	sheet 2 of 3
				0° ±2'	XX*13	scale	2:1	74390	size
				dr	D WAUGHEN	1.5.98		type	CUSTOMER Drawing
				enr	T LEMKE	1.5.98			
				chr	T LEMKE	1.5.98			
				appd	T LEMKE	1.5.98			
sheet index	revision sheet								

NOTES:

①. MAT'L:

HOUSING: LCP

CONTACT: COPPER ALLOY

PLATING

CONTACT: (SEE TABLE ON SHEET1)

SOLDER BALL: (SEE TABLE ON SHEET1)

EUTECTIC SnPb OR LEAD FREE

95.5Sn/4Ag/0.5Cu

②. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.

③. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.

④. PLATING FOR -2XX SERIES DASH NOS: Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.

⑤. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION

⑥. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

A

A

B

B

mat'l. code SEE NOTE 1		surface ASME Y14.5 ✓		tolerance ASME Y14.5		projection 		product family MEG-ARRAY		
ltr	ecr no	dr	date	tolerances unless otherwise specified				title		
L				angles	time/pt	MM		8mm RECP. ASSY.		
				0° ±2'		scale 2:1		10x40= 400 POS.		
		dr	D WAUGHEN		1.5.98			dwg no		
		enr	T LEMKE		1.5.98			sheet 3 of 3		size
		chr	T LEMKE		1.5.98			74390		A4
		appd	T LEMKE		1.5.98			type CUSTOMER Drawing		
sheet index	revision sheet									